
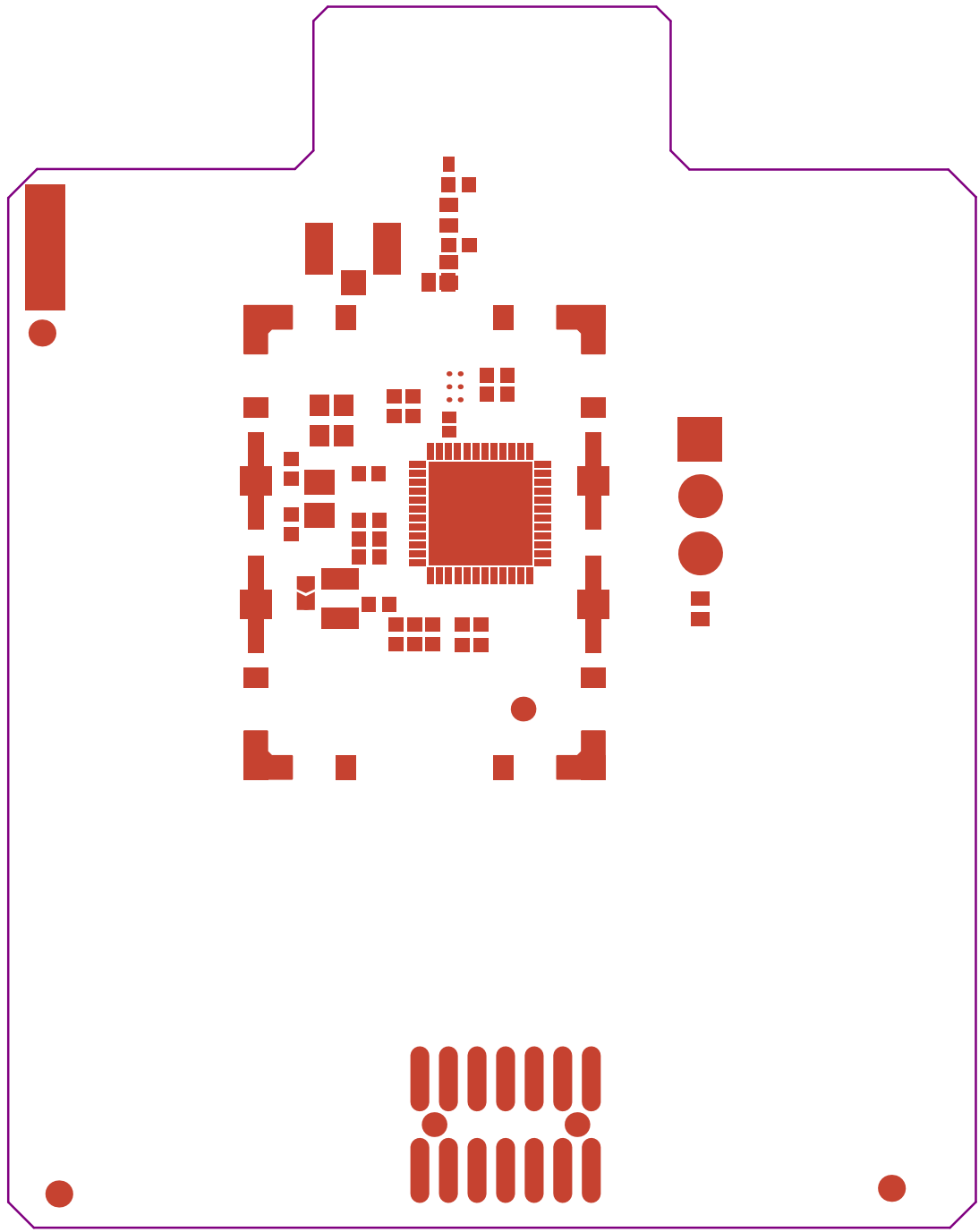

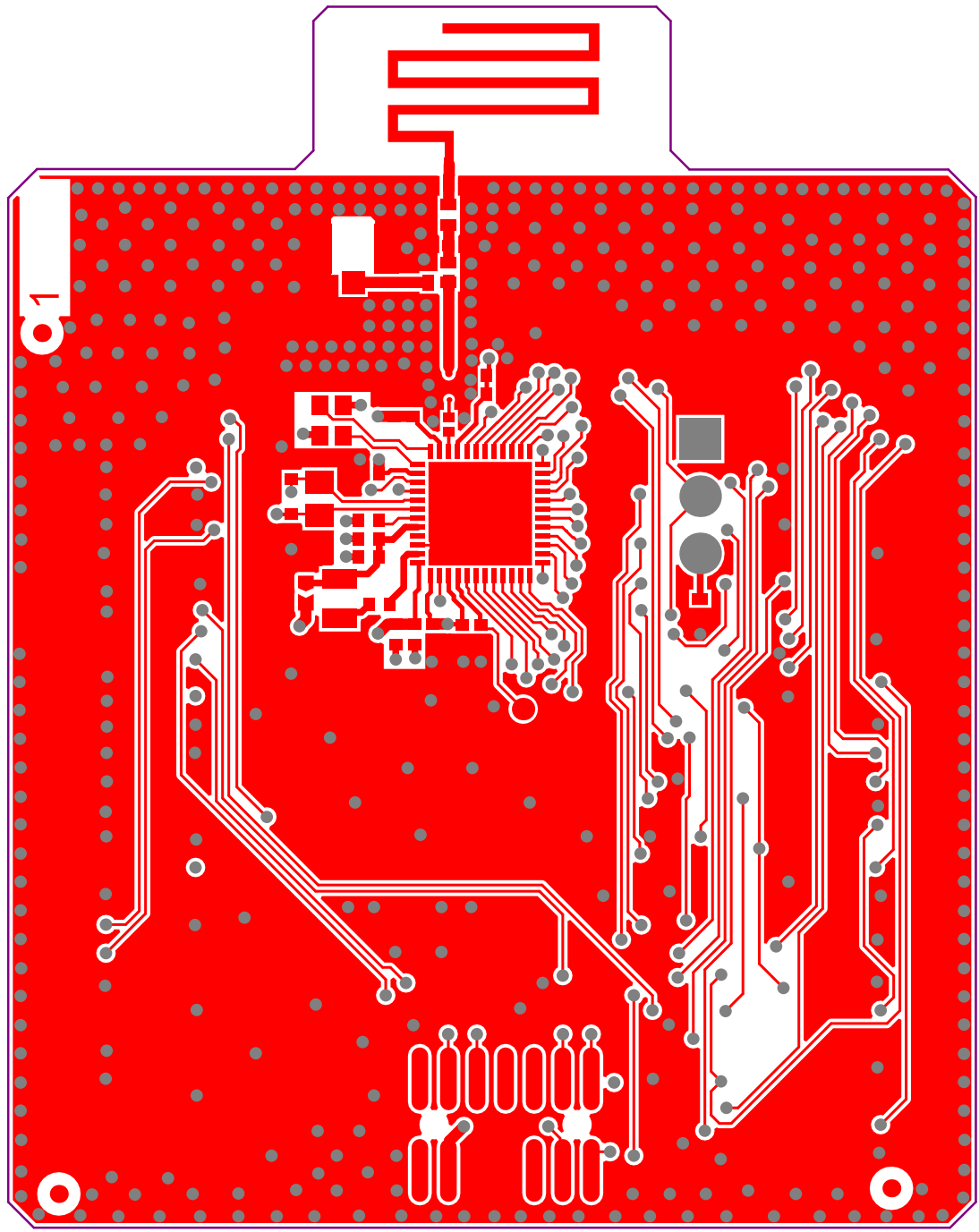



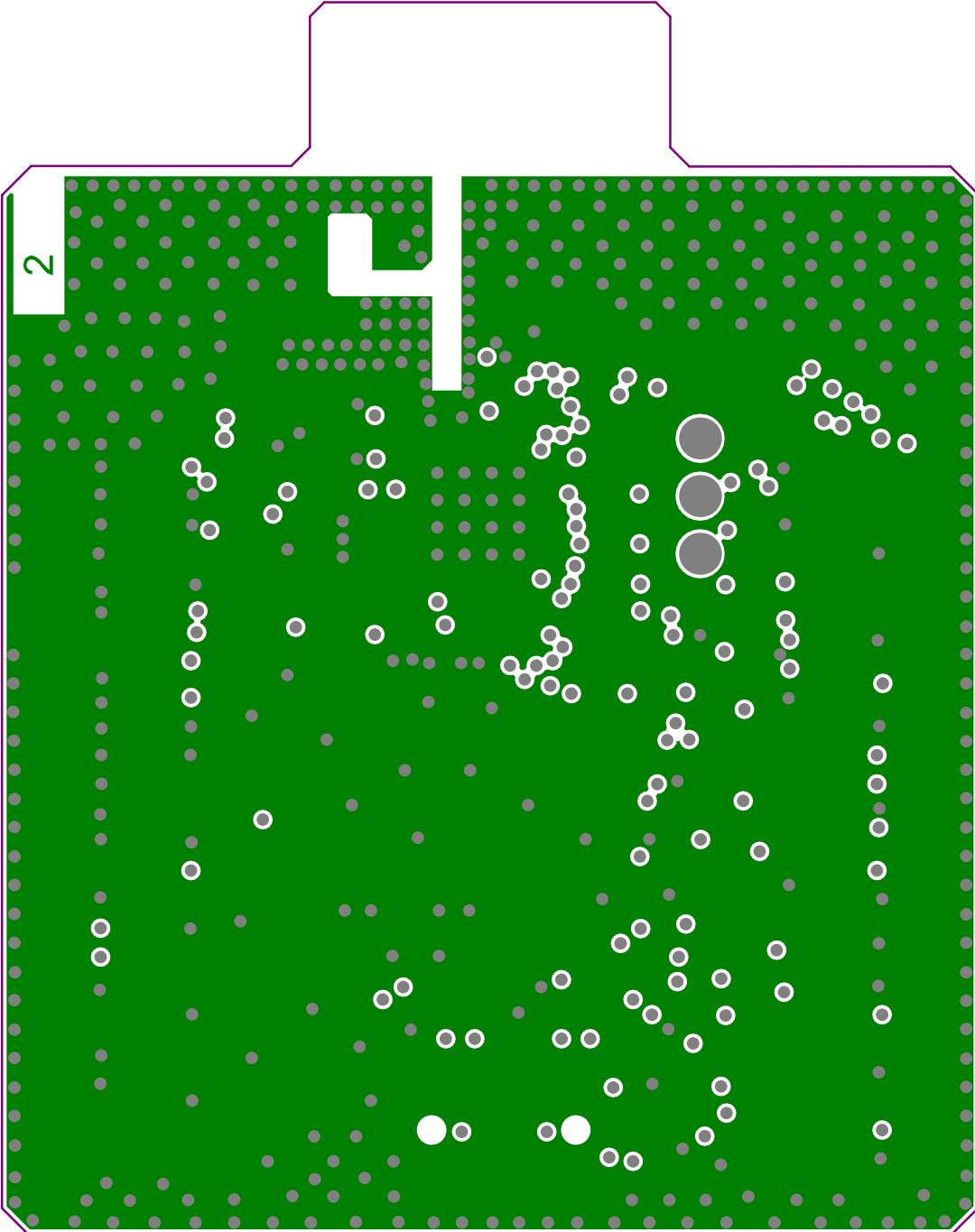
Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	



Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	

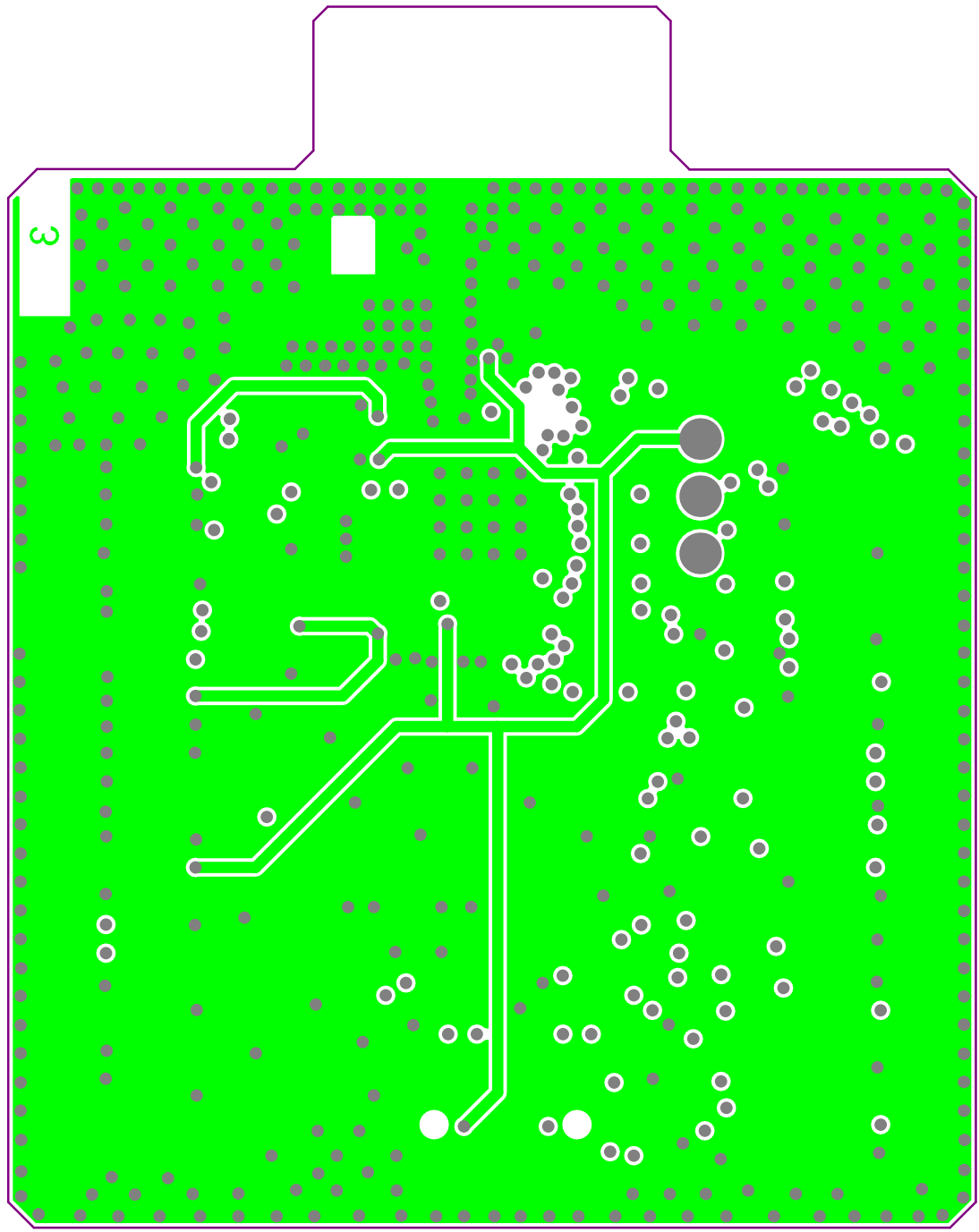



Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	

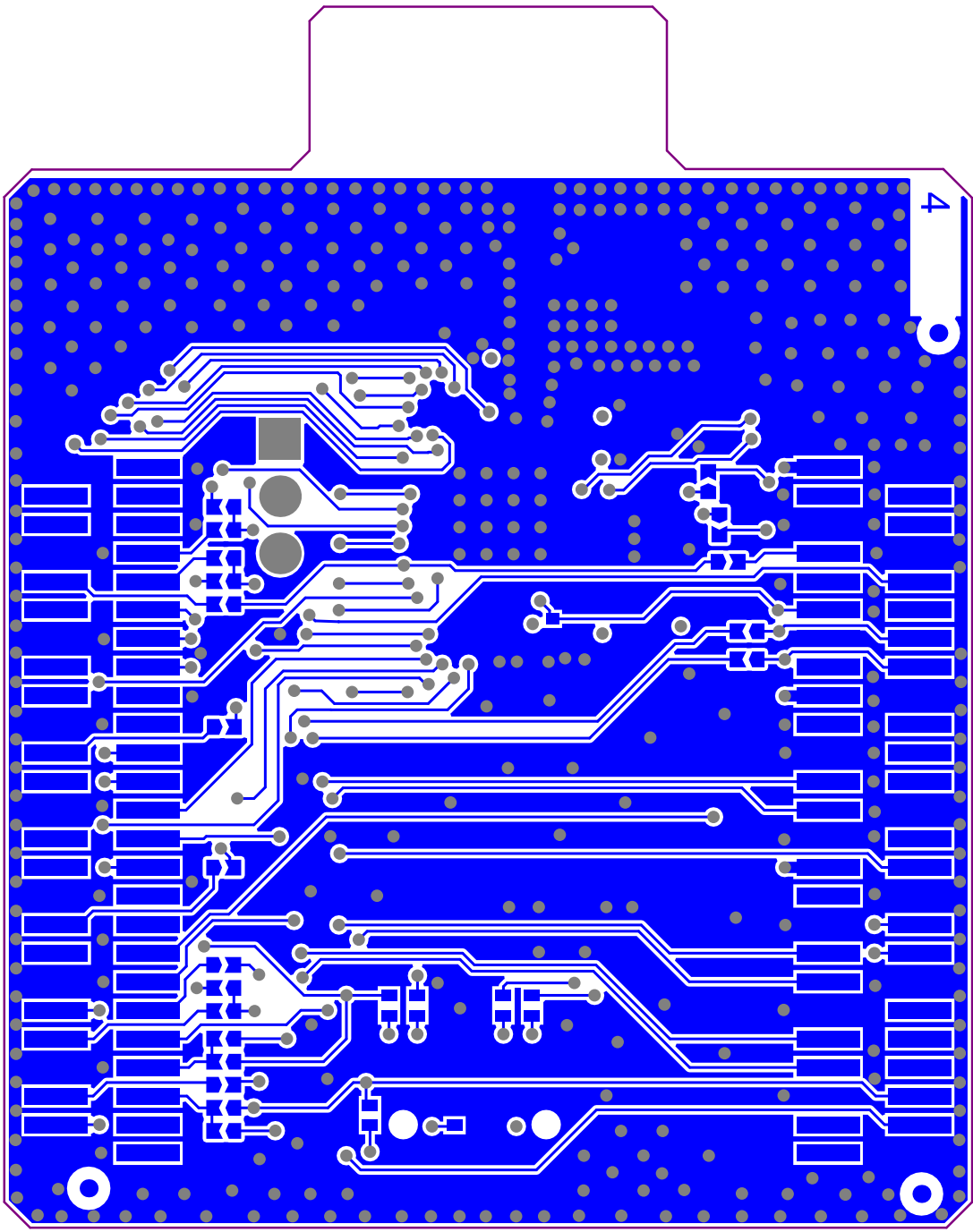



Project: MiniBoard_WB07_QFN48_SMPS	
Layer: Internal 1	Gerber: .G1
Variant: [No Variations]	Ref: MB2119
Date: 17-OCT-2023	Rev: A

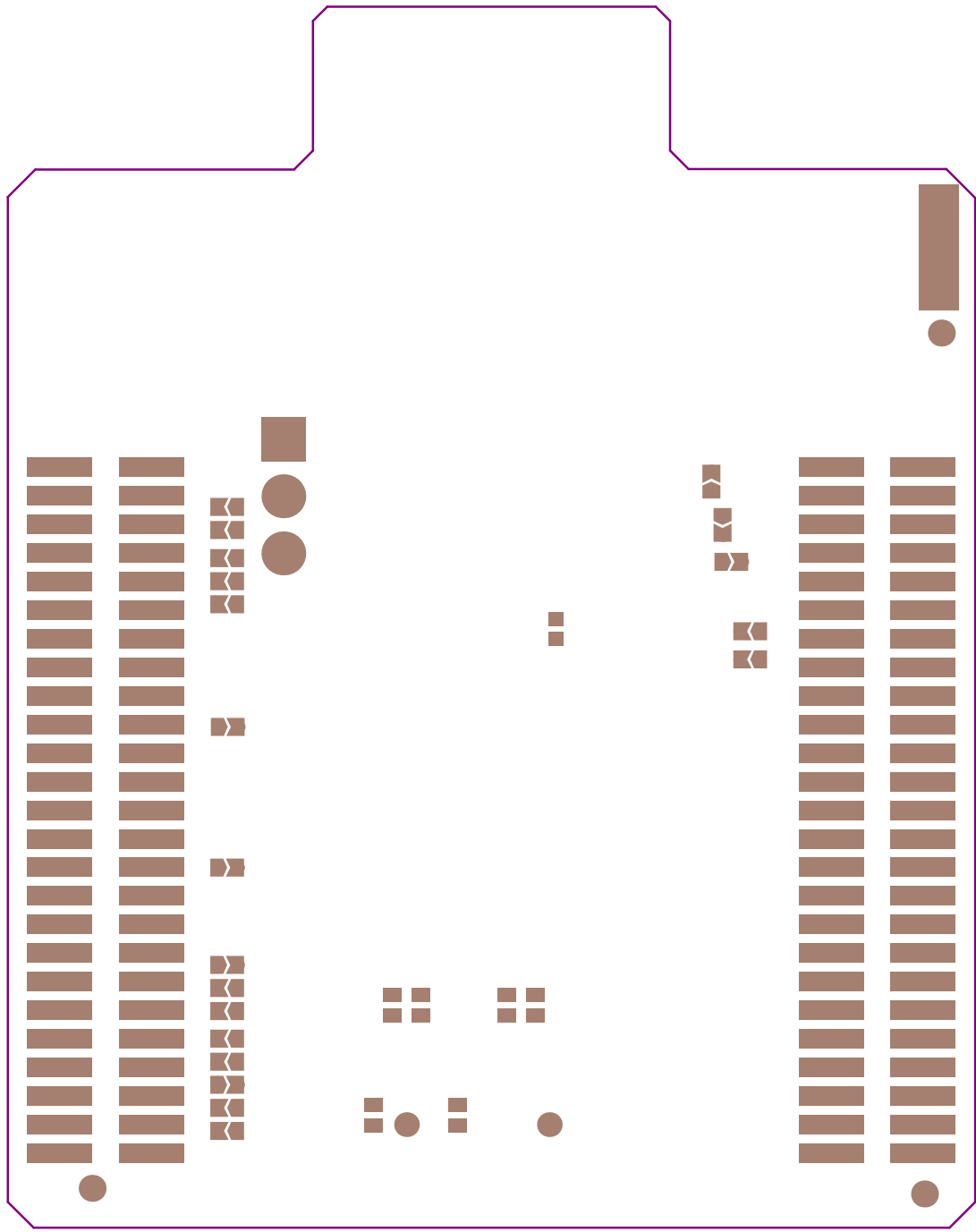





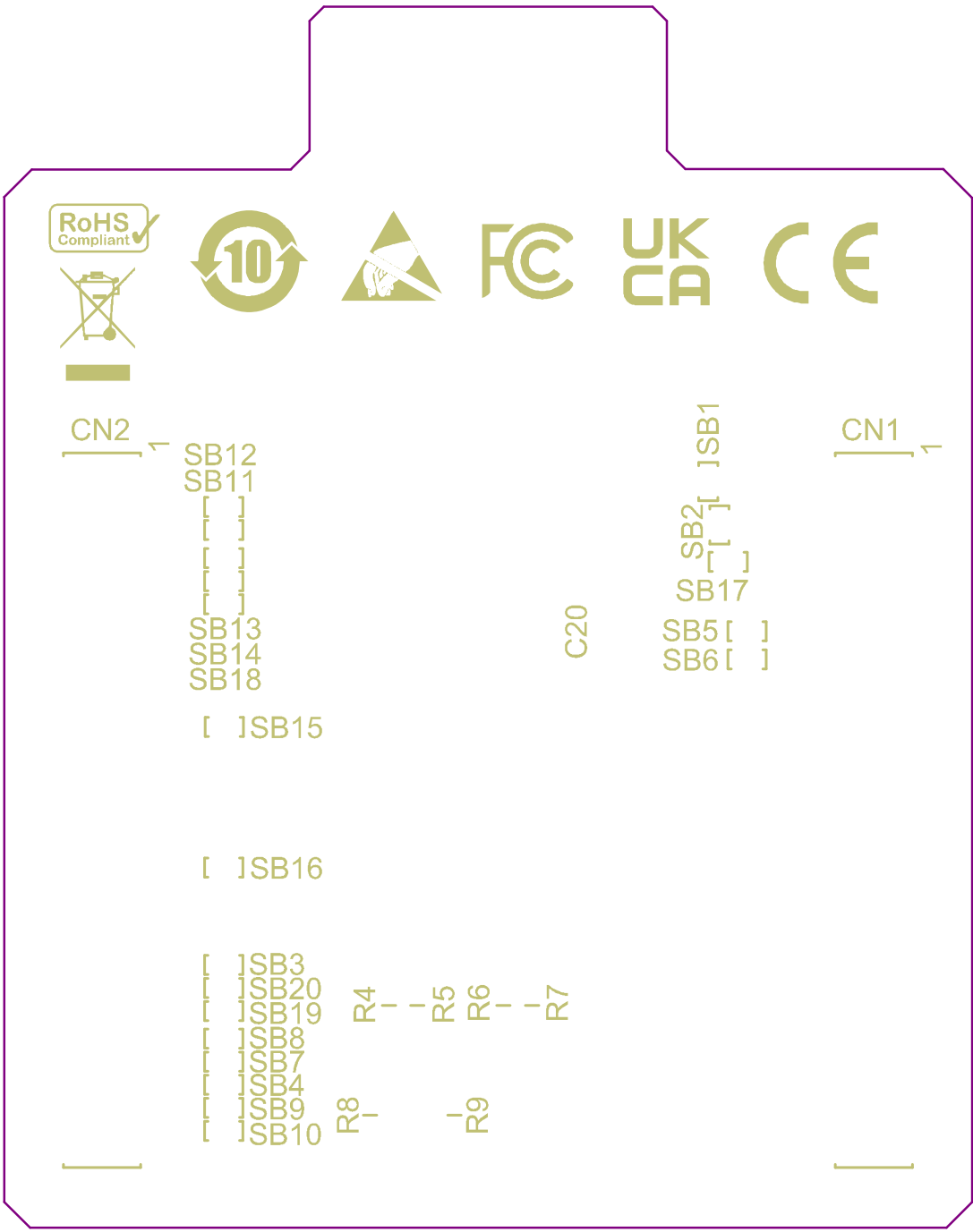
Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Internal 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	




Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	



Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	



Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☒ NO

☒ BLUE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☐ RED

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

TG-170

☒ TG-150

☐ TG-140

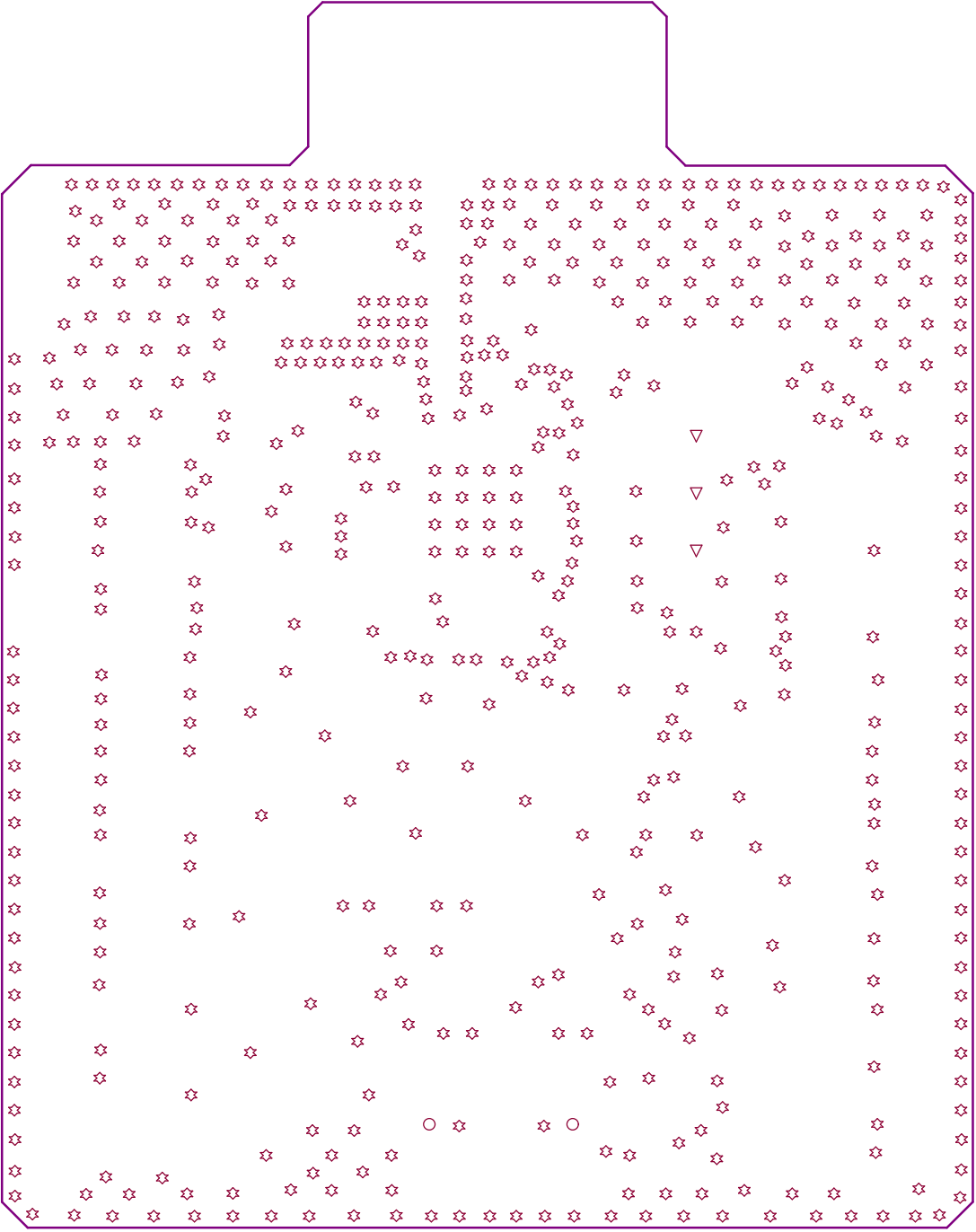
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL :

☒ SOLDERMASK


☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.042mm		
	Dielectric 1	FR-4	0.106mm	4.2	
2	Internal 1		0.035mm		
	Dielectric 3		1.248mm	4.2	
3	Internal 2		0.035mm		
	Dielectric 2		0.106mm	4.2	
4	Bottom Layer		0.042mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
☆	554	0.35mm (13.78mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v55h35m0mx0	
○	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m105p-1	
▽	3	1.00mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	
	559 Total								

Project: MiniBoard_WB07_QFN48_SMPS		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2119	
Date: 17-OCT-2023	Rev: A	